



SCALE 4:1

WLCSP4, 0.84x0.84x0.3

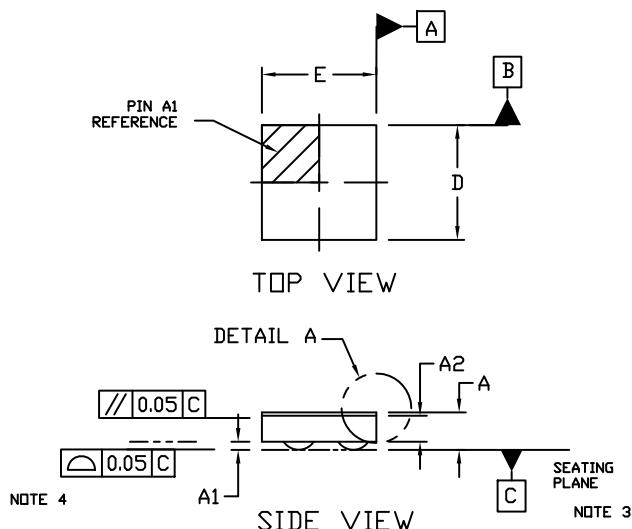
CASE 567VY

ISSUE O

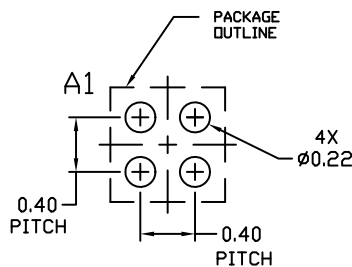
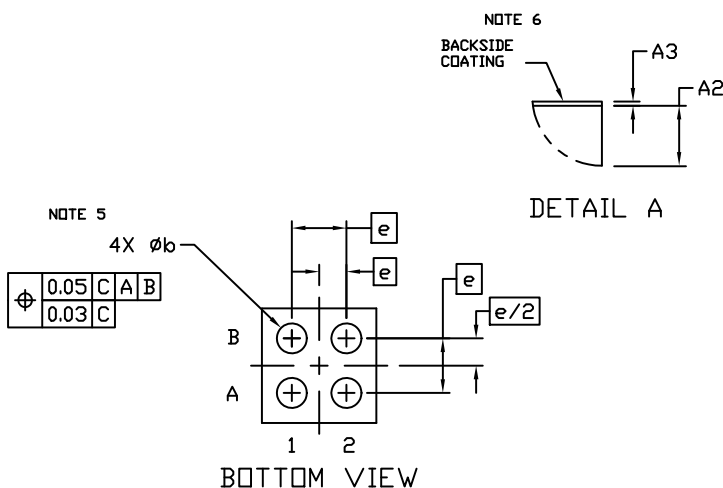
DATE 21 FEB 2018

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.25	0.275	0.30
A1	0.04	0.06	0.08
A2	0.19 REF		
A3	0.025 REF		
b	0.20	0.22	0.24
D	0.79	0.84	0.89
E	0.79	0.84	0.89
e	0.40 BSC		



GENERIC
MARKING DIAGRAM*



X = Specific Device Code
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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